

OP4177 Die Revision, Wafer Fabrication Process Change & Assembly Site Transfer

Qualification Results Summary of OP4177 Die Revision, Wafer Fabrication Process Change & Assembly Site Transfer to ASE Chung-Li

QUALIFICATION PLAN / STATUS			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
Early Life Failure Rate (ELFR)	<i>MIL-STD-883, M1015</i>	3 x 800	Pass
High Temperature Operating Life (HTOL)	<i>JEDEC JESD22-A108</i>	3 x 77	Pass
High Temperature Storage Life (HTSL)	<i>JEDEC JESD22-A103</i>	1 x 77	Pass
Solder Heat Resistance (SHR)*	<i>JEDEC J-STD-020</i>	3 x 11	Pass
Temperature Cycle (TC)*	<i>JEDEC JESD22-A104</i>	3 x 77	Pass
Temperature, Humidity, Bias (THB)*	<i>JEDEC JESD22-A101</i>	3 x 77	Pass
Latch-Up	<i>JEDEC JESD78</i>	3/test	Pass ±200 mA, ±22.5 V
Electrostatic Discharge <i>Human Body Model</i>	<i>JEDEC JS-002</i>	3/voltage	Pass ±1000 V
Electrostatic Discharge <i>Field-Induced Charged Device Model</i>	<i>JEDEC JESD22-A114</i>	3/voltage	Pass ±1250 V

*Preconditioned per JEDEC J-STD-020 Level 1